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(12) **United States Design Patent**
Chung

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(54) **HEAT SINK FOR MEMORY MODULES**

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(**) Term: **15 Years**

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(51) **LOC (13) Cl.** **13-03**

(52) **U.S. Cl.**
USPC **D13/179**

(58) **Field of Classification Search**
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H01L 23/3672; H01L 23/3675; H01L
23/3677; H01L 23/4093; H01L 23/467;
G06F 1/20; H05K 7/2039; H05K 7/20509
See application file for complete search history.

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(57) **CLAIM**

The ornamental design for a heat sink for memory modules, as shown and described.

DESCRIPTION

FIG. 1 is a top, front perspective view of the heat sink for memory modules;
 FIG. 2 is a front view thereof;
 FIG. 3 is a rear view thereof;
 FIG. 4 is a left side view thereof;
 FIG. 5 is a right side view thereof;
 FIG. 6 is a top view thereof; and,
 FIG. 7 is a bottom view thereof.

1 Claim, 5 Drawing Sheets

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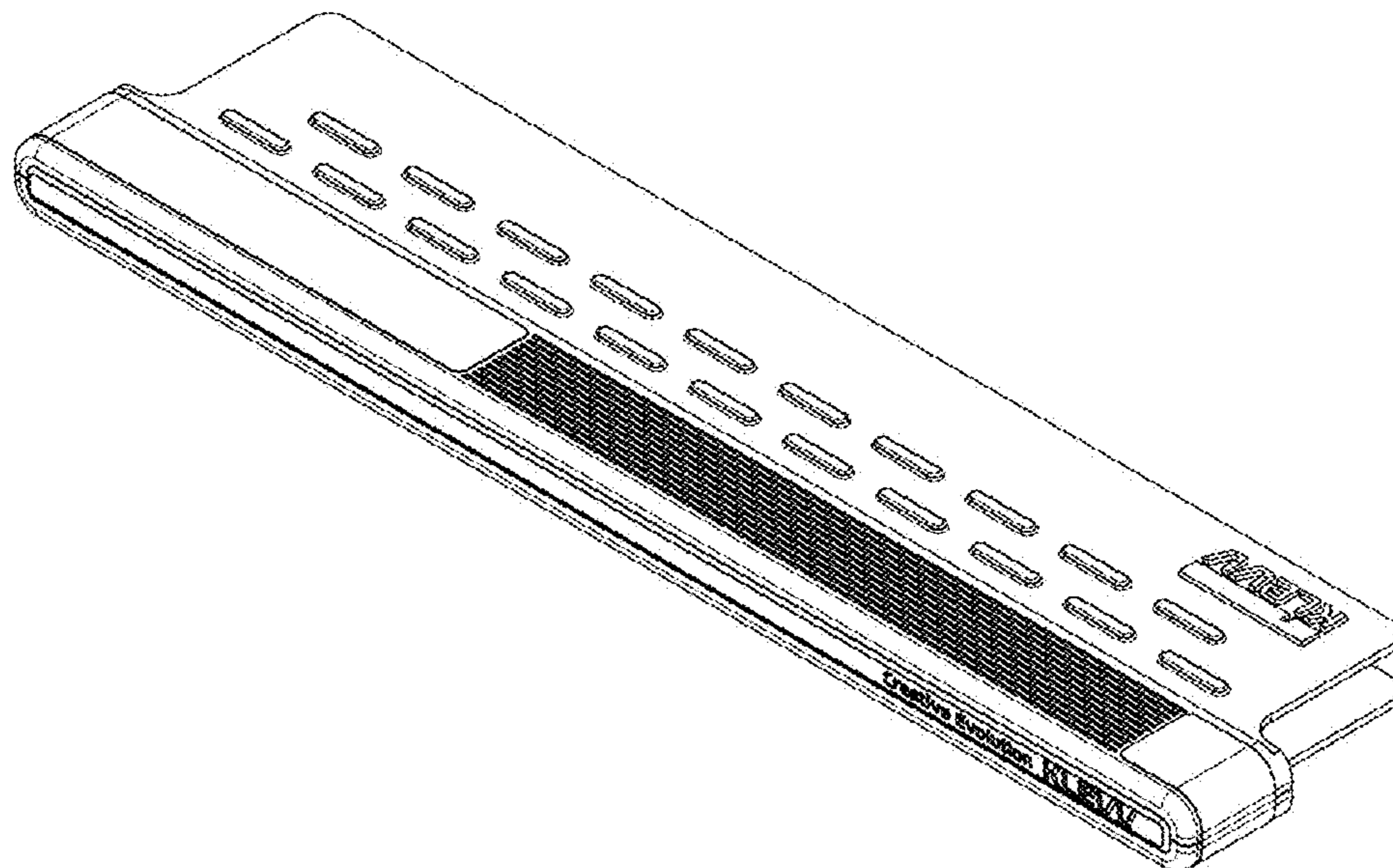
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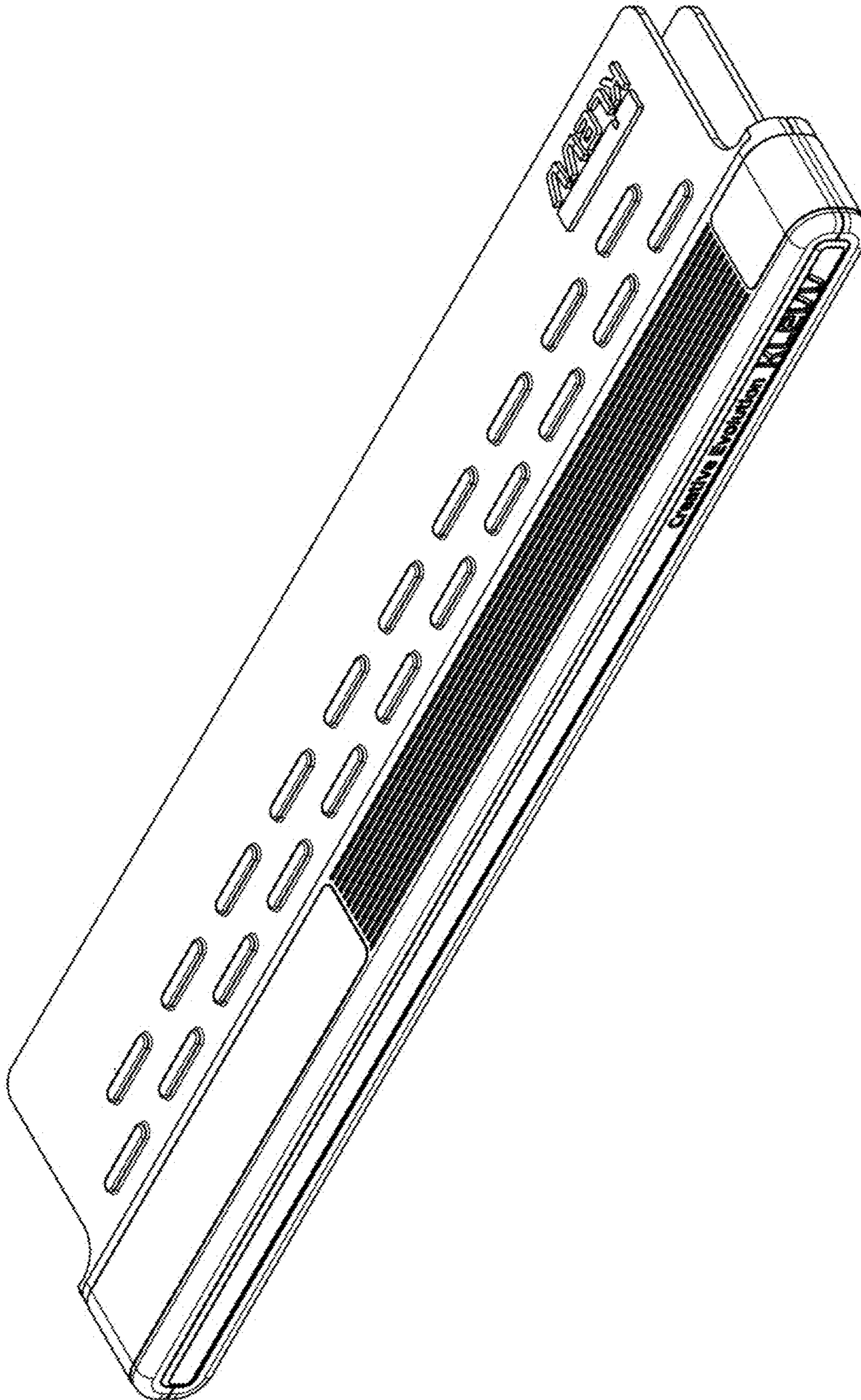


FIG. 1

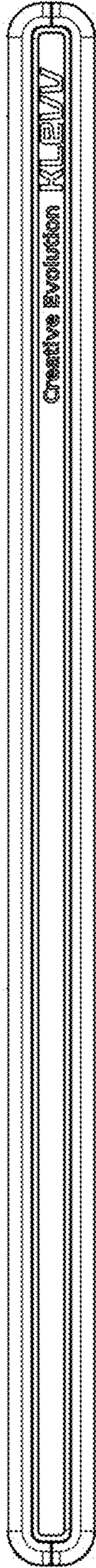


FIG. 2

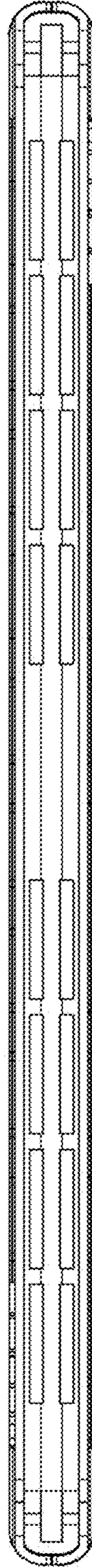


FIG. 3

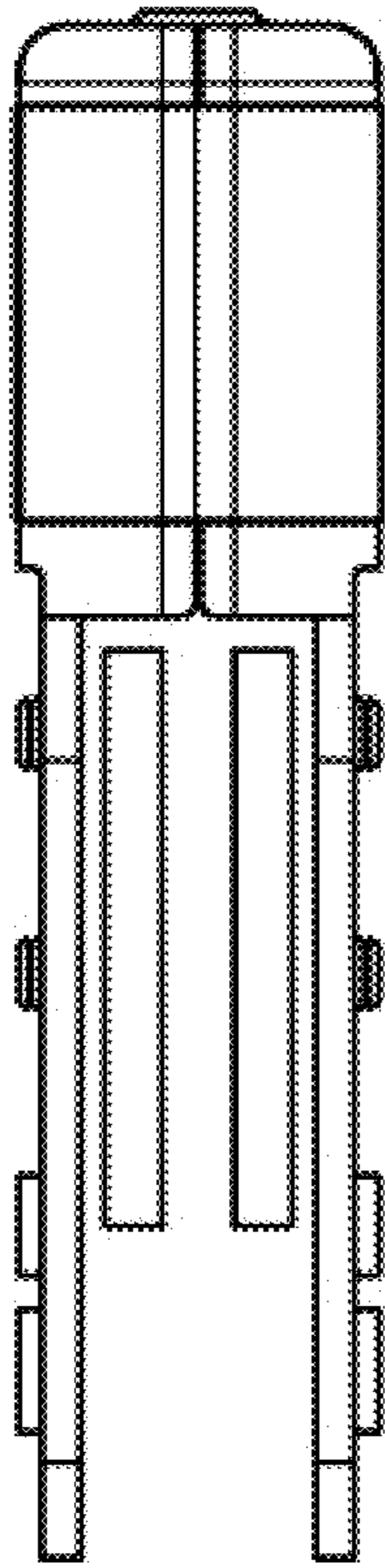


FIG. 4

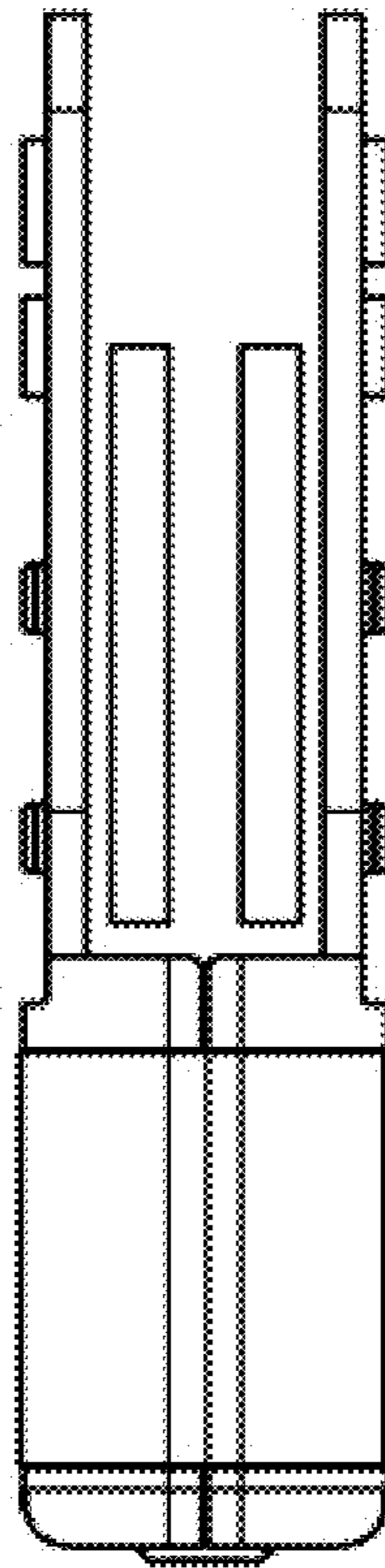


FIG. 5

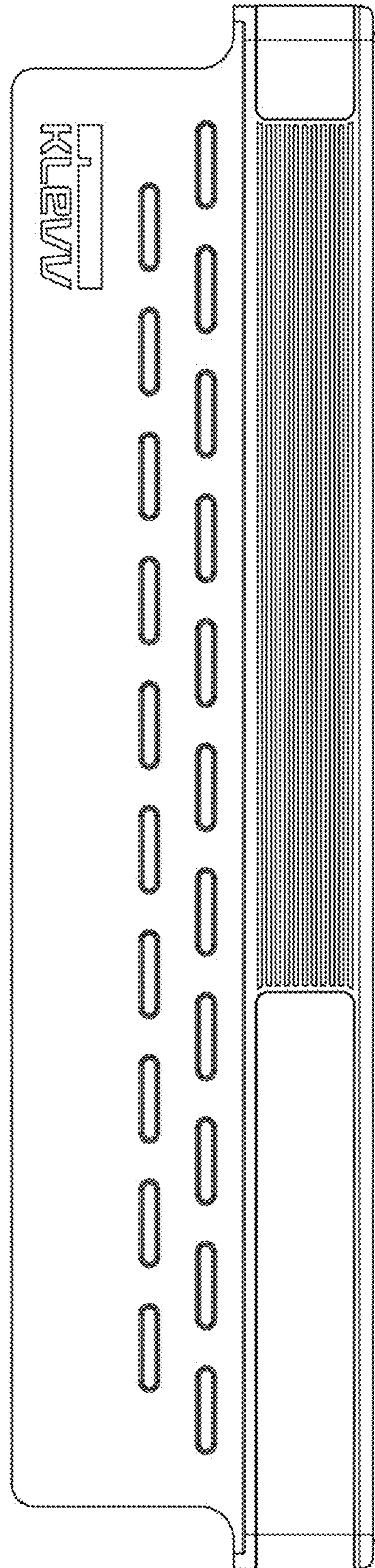


FIG. 6

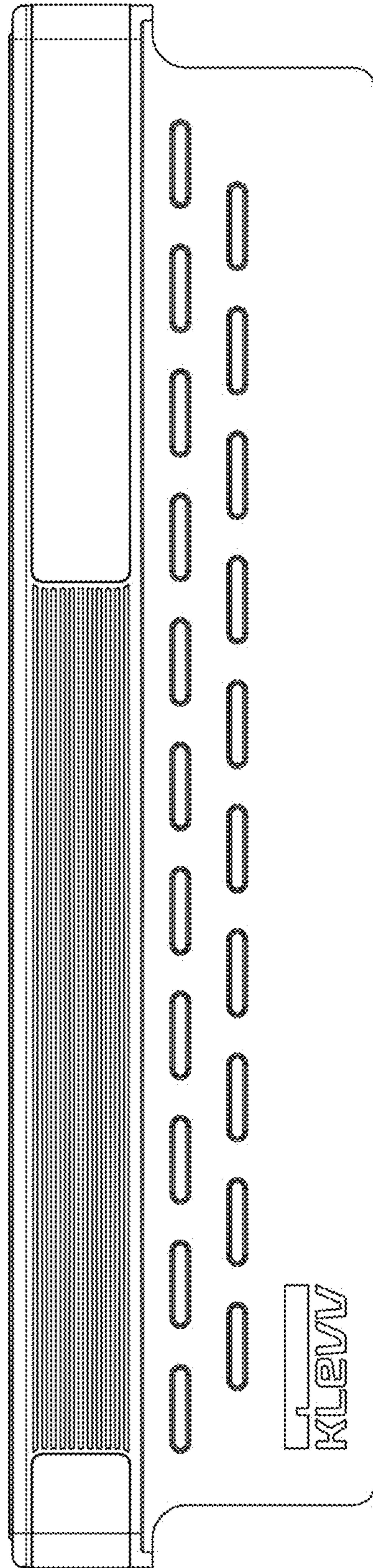


FIG. 7